

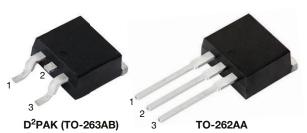
Vishay Semiconductors

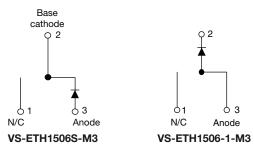
COMPLIANT

HALOGEN

FREE

Hyperfast Rectifier, 15 A FRED Pt®





PRIMARY CHARACTERISTICS					
I _{F(AV)}	15 A				
V _R	600 V				
V _F at I _F	1.25 V				
t _{rr} (typ.)	21 ns				
T _J max.	175 °C				
Package	D ² PAK (TO-263AB), TO-262AA				
Circuit configuration	Single				

FEATURES

- · Hyperfast recovery time
- · Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- Designed and qualified according to JEDEC®-JESD 47
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION / APPLICATIONS

Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS		
Repetitive peak reverse voltage	V_{RRM}		600	V		
Average rectified forward current	I _{F(AV)}	T _C = 139 °C	15	Α		
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	160	A		
Operating junction and storage temperatures	T _J , T _{Stg}		-55 to +175	°C		

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL TEST CONDITIONS				MAX.	UNITS
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	600	-	-	.,,
Forward voltage V _F	V _F	I _F = 15A	-	1.8	2.45	V
r orward voltage	٧F	I _F = 15 A, T _J = 150 °C	-	1.25	1.6	
Dovoroo lookaga aurrant	_	$V_R = V_R$ rated	-	0.01	15	
Reverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	20	200	μA
Junction capacitance	C _T	V _R = 600 V	-	12	-	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST (CONDITIONS	MIN.	TYP.	MAX.	UNITS
		$I_F = 1.0 \text{ A}, dI_F/dt =$	100 A/μs, V _R = 30 V	-	21	26	
Payarsa rasayany tima	+	$I_F = 15 A$, $dI_F/dt =$	100 A/μs, V _R = 30 V	-	25	36	ns
Reverse recovery time	t _{rr}	T _J = 25 °C		-	29	-	115
		T _J = 125 °C	$I_F = 15 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 390 \text{ V}$	-	65	-	
Peak recovery current	I _{RRM}	T _J = 25 °C		-	3.9	-	А
reak recovery current		T _J = 125 °C		-	7.0	-	
Deviana nagavani abaraa	0	T _J = 25 °C		-	60	-	nC
Reverse recovery charge	Q_{rr}	T _J = 125 °C		-	240	-	IIC
Reverse recovery time	t _{rr}		I _E = 15 A	-	42	-	ns
Peak recovery current	I _{RRM}	T _J = 125 °C	$dI_F/dt = 800 A/\mu s$	-	21	-	Α
Reverse recovery charge	Q _{rr}		V _R = 390 V	-	480	-	nC

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C
Thermal resistance, junction to case	R _{thJC}		-	1.3	1.51	°C/W
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	70	
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-	
Woight			-	2.0	-	g
Weight			=	0.07	-	oz.
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)
Marking dayion		Case style D ² PAK (TO-263AB)		ETH1	506S	•
Marking device		Case style TO-262AA		ETH1	506-1	

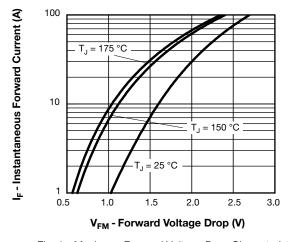


Fig. 1 - Maximum Forward Voltage Drop Characteristics

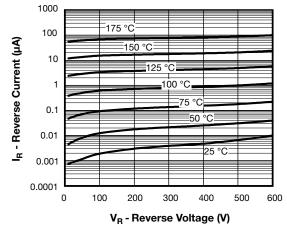


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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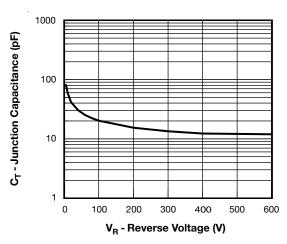


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

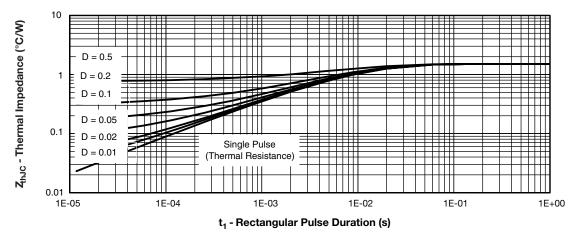


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

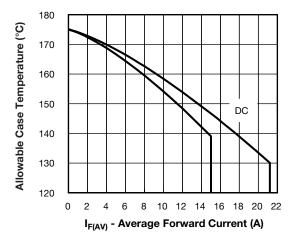


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

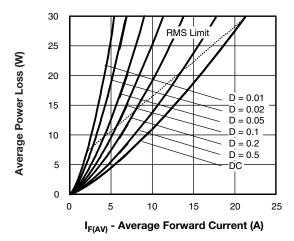
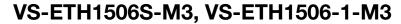


Fig. 6 - Forward Power Loss Characteristics

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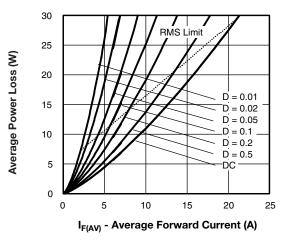


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

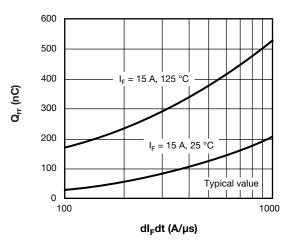
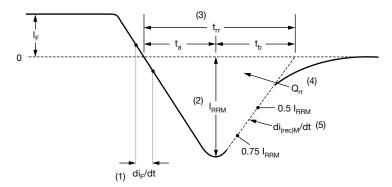


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going l_F to point where a line passing through 0.75 l_{RRM} and 0.50 l_{RRM} extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

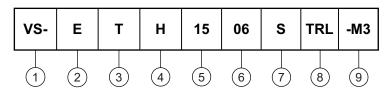


VS-ETH1506S-M3, VS-ETH1506-1-M3

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Circuit configuration

E = single

3 - T = TO-220

4 - H = hyperfast recovery time

5 - Current code (15 = 15 A)

6 - Voltage code (06 = 600 V)

- • S = D^2 PAK (TO-263AB)

- • -1 = TO-262AA

8 - • None = tube (50 pieces)

- • TRL = tape and reel (left oriented, for D²PAK (TO-263AB) package)

- TRR = tape and reel (right oriented, for D²PAK (TO-263AB) package)

9 - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)					
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION			
VS-ETH1506S-M3	50	Antistatic plastic tubes			
VS-ETH1506STRR-M3	800	13" diameter plastic tape and reel			
VS-ETH1506STRL-M3	800	13" diameter plastic tape and reel			
VS-ETH1506-1-M3	50	Antistatic plastic tubes			

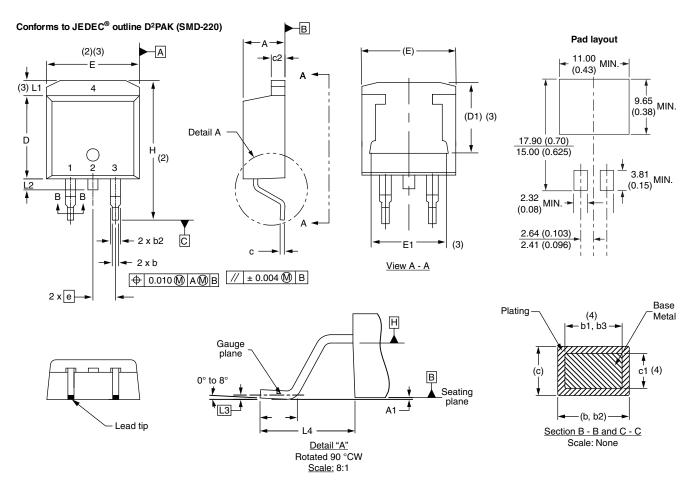
LINKS TO RELATED DOCUMENTS				
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164		
Differsions	TO-262AA	www.vishay.com/doc?96165		
Dout moulding information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444		
Part marking information	TO-262AA	www.vishay.com/doc?95443		
Packaging information	D ² PAK (TO-263AB)	www.vishay.com/doc?96424		



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D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100	BSC	
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010	BSC	
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

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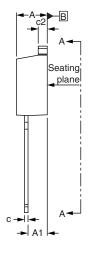


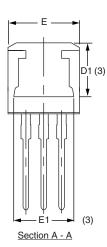
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TO-262AA

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262 (2) (3) (3) Ď L2 В (2)





0.010 M AM B

2 x e

Lead assignments



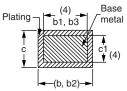
Diodes 1. - Anode (two die)/open (one die)

2., 4. - Cathode

3. - Anode

-3 x b2

-3 x b



Section B - B and C - C Scale: None

SYMBOL	MILLIN	METERS	INCHES		NOTES
STINIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
Е	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100) BSC	
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
 (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- Controlling dimension: inches

 Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)

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